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NAME OF INVENTOR(S): Yew	
RECEIPT DATE & SERIAL NO.: Serial No.: 10/612,129 Filing Date: 7/2/2003	
TITLE OF INVENTION: DIRECT ATTACHMENT OF SEMICONDUCTOR CHIP TO ORGANIC SUBSTRATE	
TI FILE NO.: TI-26239.1	DEPOSIT ACCT. NO.: 20-0668
FAXED: 10/21/2004 DUE: 10/06/2004 ATTY/SEC'Y: WDS:tlc	

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RESIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Yew
Serial No: 10/612,129
Filed: 7/2/2003
For: DIRECT ATTACHMENT OF SEMICONDUCTOR CHIP TO ORGANIC
SUBSTRATE

Docket No: TI-26239.1
Examiner: Cao, Phat X.
Art Unit: 2814

RESPONSE UNDER 37 C.F.R. § 1.116

Assistant Commissioner For Patents
Washington, DC 20231

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Tommy Chambers
Tommy Chambers

Dear Sir:

Responsive to the Office Action mailed August 6, 2004 in connection with the
above identified application, Applicants respectfully submit the following remarks.